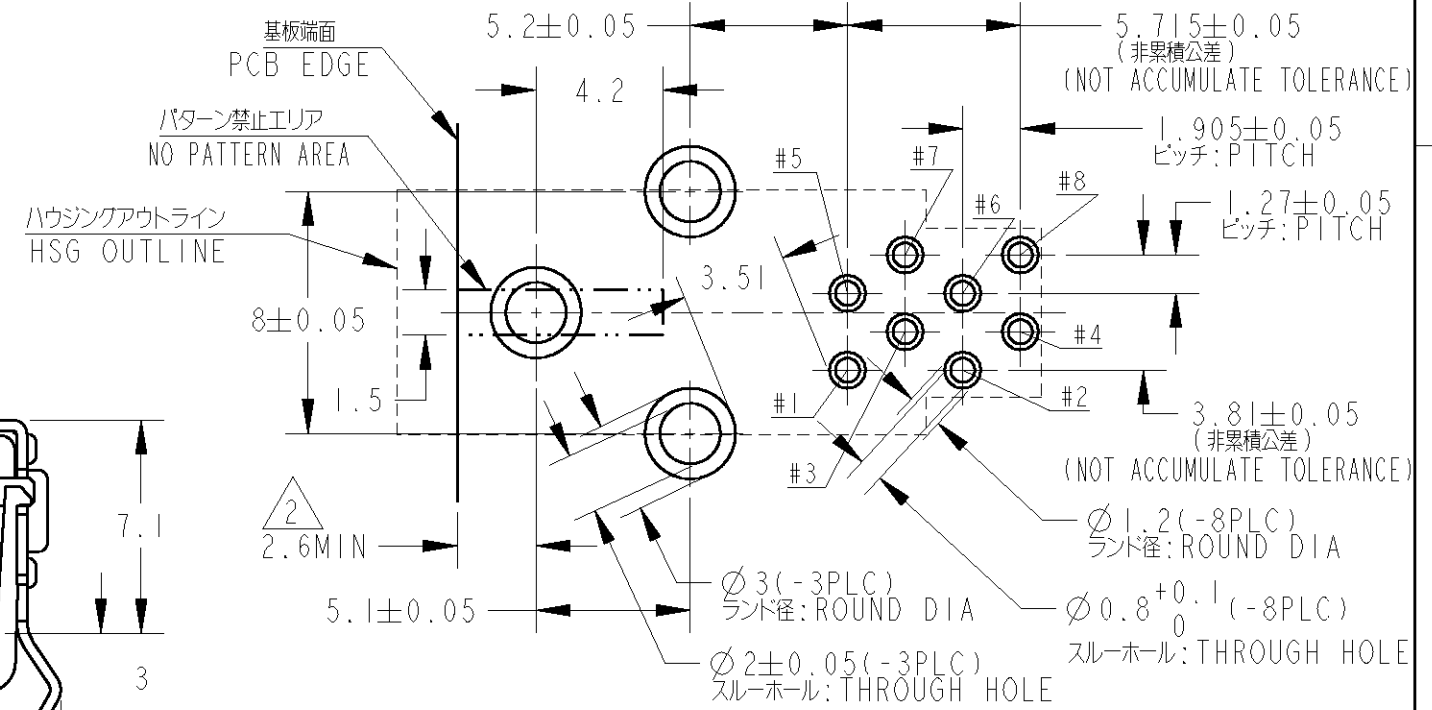
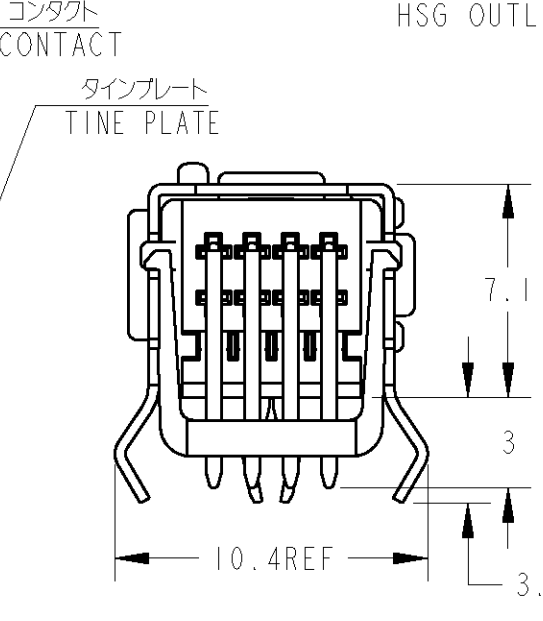
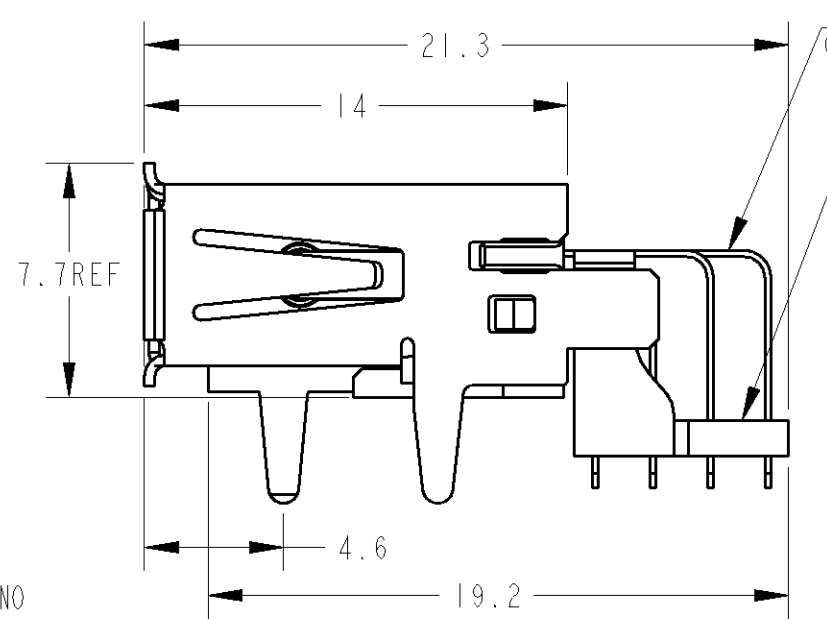
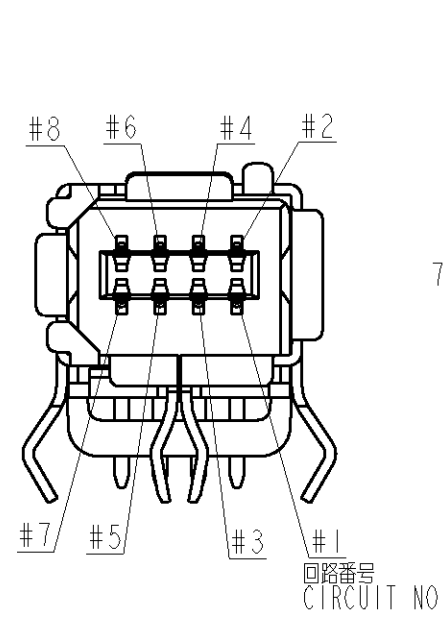
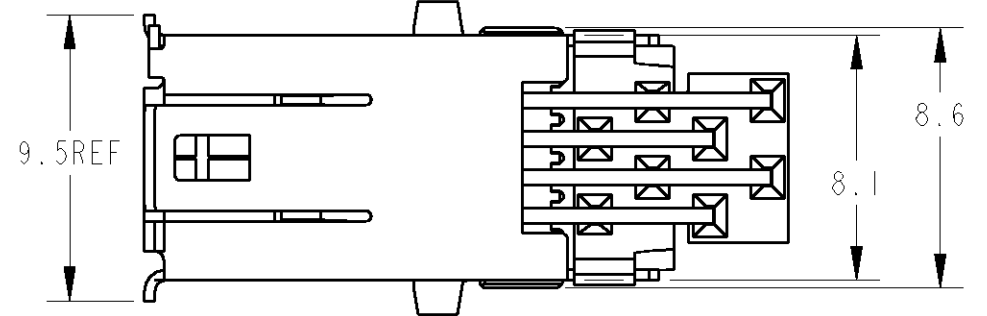
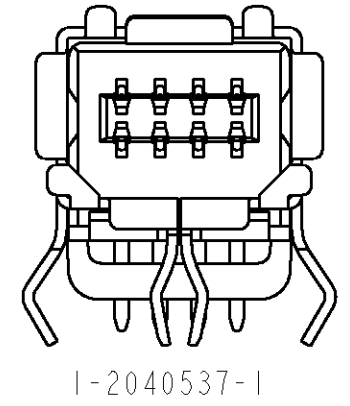
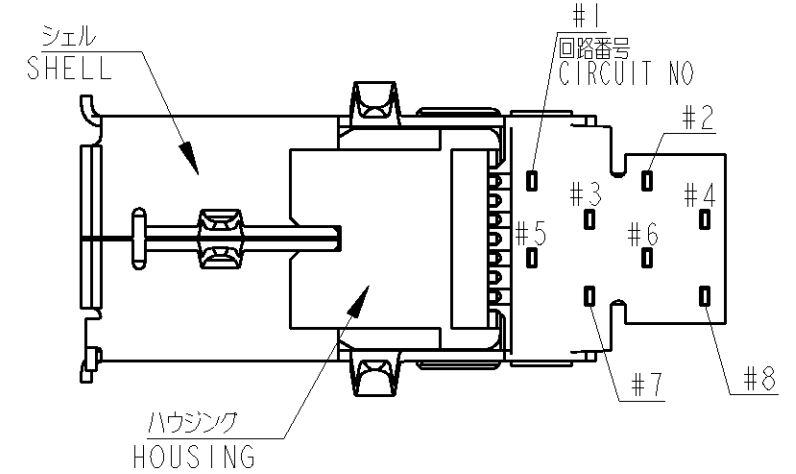


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LOC	DIST	REVISIONS					
		P	LTR	DESCRIPTION	DATE	DWN	APVD
J	-		A	RELEASED	14JUL2008	M.M	I.H



推奨基板寸法 (実装面側) ±1.6
 RECOMMENDED BOARD DIMENSION (CONNECTOR SIDE) ±1.6



1. MATERIAL AND FINISH
 CONTACT
 COPPER ALLOY
 UNDER ALL SURFACE NICKEL 1.27µm MIN
 TOP CONTACT AREA : GOLD 0.5µm MIN
 SOLDERING AREA : TIN PLATE
 HOUSING
 THERMO PLASTIC (UL94V-0)
 SHELL
 COPPER ALLOY
 UNDER ALL SURFACE NICKEL
 TOP ALL SURFACE TIN

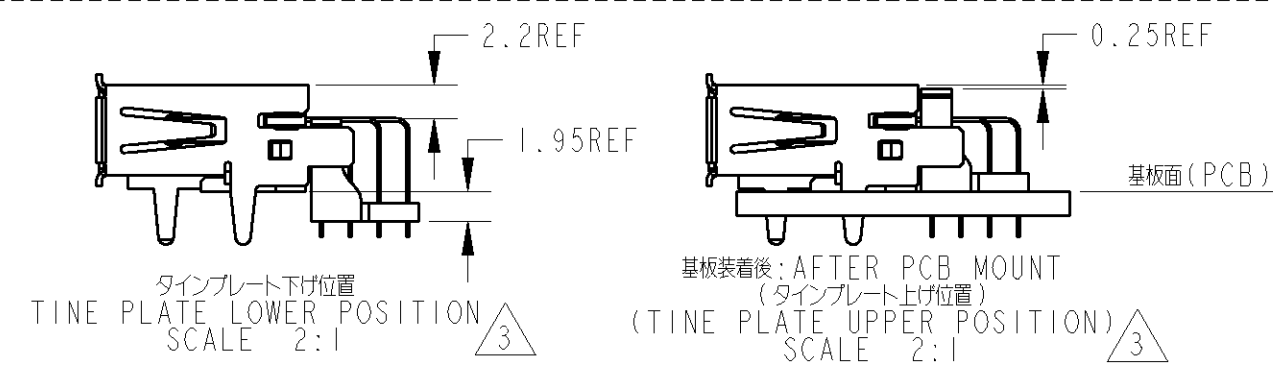
1. 材料及び仕上げ
 コントラクト
 材料: 銅合金
 全面ニッケル下地めっき 1.27µmMIN
 接点部: 金めっき 0.5µmMIN
 半田付け部: 錫めっき
 ハウジング
 材料: 熱可塑性樹脂 (難燃性UL94V-0)
 シェル
 材料: 銅合金
 全面ニッケル下地めっき
 全面錫めっき

2. DIMENSION DECIDED BY CUSTOMER.
 3. TINE PLATE CAN MOVE UP AND DOWN.

2. 顧客決定寸法
 3. タインプレートは可動式

AS SHOWN AS : 2040537-1

8	D-SHAPE TYPE-II	1-2040537-1
8	D-SHAPE TYPE-I	2040537-1
POS	DESCRIPTION	PART NO



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 IT IS SUBJECT TO CHANGE AND THE CONTROLLING ENGINEERING ORGANIZATION
 SHOULD BE CONTACTED FOR THE LATEST REVISION.

DWN	M. MAEBASHI	14JUL2008
CHK	I. HASEGAWA	14JUL2008
APVD	I. HASEGAWA	14JUL2008
PRODUCT SPEC	108-78405	
APPLICATION SPEC		
WEIGHT	-	

INDUSTRIAL MINI I/O CONN
 1.27mm PITCH
 HDR ASSY (DIP/H-TYPE) 8POS

SIZE	A3	CAGE CODE	00779	DRAWING NO	2040537	RESTRICTED TO	-
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CUSTOMER DRAWING SCALE 4:1 SHEET 1 OF 1 REV A

Mouser Electronics

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